

Product / Package Information

Package	LFCSP
Body Size (mm)	9X7X0.95
Lead Count	41
Terminal Finish	NiPdAu
MS Number	MS012763B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes
Last Updated	19-Sep-19

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.91E-02	88.00	880000	61.85	618506
Thermosets	Epoxy & Phenol Resin	Proprietary	3.81E-03	11.50	115000	8.08	80828
Other inorganic materials	Carbon black	1333-86-4	1.66E-04	0.50	5000	0.35	3514
Subtotal			3.31 E-02	100.00	1000000	70.28	702848

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.38 E-03	97.5	975000	2.93	29276
Copper & its alloys	Iron	7439-89-6	3.32 E-05	2.35	23500	0.07	706
Copper & its alloys	Zinc	7440-66-6	1.70 E-06	0.12	1200	0.00	36
Copper & its alloys	Phosphorus	7723-14-0	4.24 E-07	0.03	300	0.00	9
Subtotal			1.41 E-03	100.00	1000000	3.00	30027

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	6.24 E-04	81.91	819149	1.32	13250
Precious metals	Palladium	7440-05-3	9.73 E-05	12.77	127660	0.21	2065
Precious metals	Gold	7440-57-5	4.05 E-05	5.32	53191	0.09	860
Subtotal			7.62 E-04	100.0	1000000	1.62	16175

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Gold	7440-57-5	4.02 E-04	99.0	990000	0.86	8613
Precious metals	Palladium	7440-05-3	4.06 E-06	1.0	10000	0.00	0
Subtotal			4.06 E-04	100.0	1000000	0.86	8613

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silicon	7440-21-3	7.00 E-03	100.0	1000000	14.86	148589

Die Attach 1

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.10 E-03	77.00	770000	6.57	65748
Other organic materials	Acrylic resin	Proprietary	2.82 E-04	7.00	70000	0.60	5977
Other organic materials	Acrylate	Proprietary	2.21 E-04	5.50	55000	0.47	4696
Other organic materials	Polybutadiene derivative	Proprietary	1.81 E-04	4.50	45000	0.38	3842
Other organic materials	Epoxy resin	Proprietary	1.01 E-04	2.50	25000	0.21	2135
Other organic materials	Butadiene Copolymer	Proprietary	6.03 E-05	1.50	15000	0.13	1281
Others	Additive	Proprietary	6.03 E-05	1.50	15000	0.13	1281
Others	Peroxide	Proprietary	2.01 E-05	0.50	5000	0.04	427
Subtotal			4.02 E-03	100.0	1000000	8.54	85388

Die Attach 2

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Epoxy resin	Trade secret	3.35 E-04	85	850000	0.71	7106
Other organic materials	Acrylic resin	Trade secret	5.91 E-05	15	150000	0.13	1254
Subtotal			3.94 E-04	100.0	1000000	0.84	8360

Package Totals			Weight (g) 4.71 E-02			Percentage (%) 100	PPM 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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